

Product Features

- High dynamic range downconverter with integrated LO and IF amplifiers
- Dual channels for diversity
- +28 dBm Input IP3
- +11.5 dBm Input P1dB
- RF: 1900 2700 MHz
- IF: 65 300 MHz
- +5V Single supply operation
- RoHS-compliant / Pb-free 6x6mm 28-pin QFN package
- Low-side LO configuration

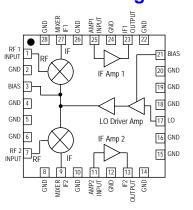
Product Description

The CV221-2A is a dual-channel high-linearity down-converter designed to meet the demanding performance, functionality, and cost goals of current and next generation mobile infrastructure basestations and repeaters. It provides high dynamic range performance in a low profile RoHS-compliant/lead-free surface-mount leadless package that measures 6 x 6 mm square.

It is ideally suited for high dynamic range receiver front ends using diversity receive channels. Functionality includes frequency conversion and IF amplification, while an integrated LO driver amplifier powers the passive mixer. The MCM is implemented with reliable and mature GaAs MESFET and InGaP HBT technology.

Typical applications include frequency downconversion used in 3G W-CDMA and WiMax basestation transceiver or repeater applications.

Functional Diagram



Specifications (1)

| Parameters | Units | Min | Тур | Max | Min | Тур | Max | Comments |
|---------------------------------|--------|-------------|------------|-------------|------|-------------|------------|--------------------------|
| RF Frequency Range | MHz | 1900 – 2400 | | 2500 – 2700 | | | | |
| LO Frequency Range | MHz | 1 | 1600 – 233 | 5 | 2 | 2200 – 2565 | | |
| IF Frequency Range | MHz | | 65 - 300 | | | 135 - 300 | See note 2 | |
| % Bandwidth around IF center | | | | | | | | |
| frequency | % | | ±7.5 | | ±12 | | | See note 3 |
| IF Test Frequency | MHz | | 240 | | | 155 | | |
| SSB Conversion Gain | dB | 6.5 | 9.2 | 10.5 | 5.4 | 8.4 | 9.9 | Temp = 25 °C |
| Gain Drift over Temp (-40 to 85 | | | | | | | | |
| °C) | dB | | ±0.6 | | | ±0.6 | | Referenced to +25 °C |
| Input IP3 | dBm | +24 | +28 | | +17 | +22 | | See note 4 |
| Input 1 dB Compression Point | dBm | | +11.5 | | | +8.0 | | See note 4 |
| Noise Figure | dB | | 11 | | | 13 | | See note 5 |
| LO Input Drive Level | dBm | -2.5 | 0 | +2.5 | -2.5 | 0 | +2.5 | |
| LO-RF Isolation | dB | | 12 | | | 9 | | $P_{LO} = 0 \text{ dBm}$ |
| LO-IF Isolation | dB | | 26 | | | 26 | | $P_{LO} = 0 \text{ dBm}$ |
| RF-IF Isolation | dB | | 25 | | | 25 | | |
| Branch-Branch Isolation | dB | | 45 | | | 40 | | |
| Return Loss: RF Port | dB | | 14 | | | 12 | | |
| Return Loss: LO Port | dB | | 14 | | | 14 | | |
| Return Loss: IF Port | dB | | 13 | | | 10 | | |
| Operating Supply Voltage | V | | +5 | | | +5 | | |
| Supply Current | mA | | 315 | 330 | | 315 | 330 | See note 6 |
| Thermal Resistance | °C / W | | | 34 | | | 34 | |
| Junction Temperature | °C | | | 160 | | | 160 | See note 6 |

- 1. Specifications when using the application specific circuit (shown on page 3) with a low side LO = 0 dBm and IF = 240 MHz in a downconverting application at 25 °C.
- 2. If matching components affect the center IF frequency. Proper component values for other IF center frequencies than shown can be provided by emailing to applications.engineering@wj.com.

 3. The IF bandwidth of the converter is defined as 15% around any center frequency in its operating IF frequency range. The bandwidth is determined with external components. Specifications are valid around
- the total $\pm 7.5\%$ bandwidth. ie. with a center frequency of 240 MHz, the specifications are valid from 240 \pm 18 MHz.
- Assumes the supply voltage = +5 V. IIP3 is measured with Δf = 1 MHz with RFin = -5 dBm / tone.
 Assumes LO injection noise is filtered at the thermal noise floor, -174 dBm/Hz, at the RF, IF, and Image frequencies.
- 6. The R1 resistor can be modified for the CV221-2A to draw less current. Changing it from 13 to 18Ω is expected to have the converter draw 17mA less current so that the converter will draw about 300mA typically under LO drive, while degrading the IIP3 performance by 0.5 dB.

Absolute Maximum Rating

| Parameter | Rating |
|----------------------------|----------------|
| Operating Case Temperature | -40 to +85 °C |
| Storage Temperature | -55 to +150 °C |
| DC Voltage | +5.5 V |
| Junction Temperature | +220 °C |

Operation of this device above any of these parameters may cause permanent damage.

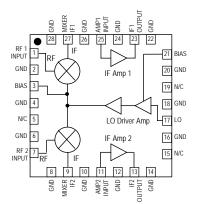
Ordering Information

| Part No. | Description |
|----------------|---|
| CV221-2AF | 1.9-2.7GHz Dual-Branch Downconverter (lead-free/RoHS-compliant 6x6mm OFN package) |
| CV221-2APCB240 | Fully Assembled Eval. Board, IF = 240MHz |
| | |

Specifications and information are subject to change without notice



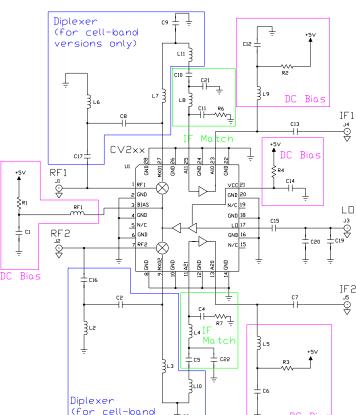
Device Architecture / Application Circuit Information



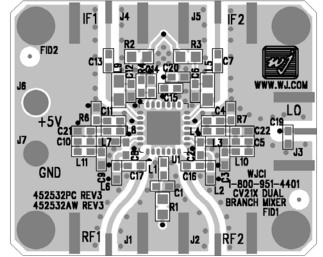
Typical 2.1 GHz Downconverter Performance Chain Analysis (Each Branch)

| | | Input | Input IP3 (dBm) | NF (dB) | Current (mA) | Cumulative Performance | | | |
|---------------------|--------------|------------------------|-----------------------|------------|--------------|------------------------|------------------------|-----------------------|------------|
| Stage | Gain (dB) | P1dB (dBm) | | | | Gain (dB) | Input P1dB (dBm) | Input IP3 (dBm) | NF (dB) |
| LO Amp / MMIC Mixer | -8.4 | 20 | 33 | 9 | 115 | -8.4 | 20 | 33 | 9 |
| IF Amplifier | 17.6 | 1 | 21 | 2.2 | 100 | 9.2 | 9 | 27.8 | 11 |
| CV221-2A | Cu | Cumulative Performance | | | 315* | 9.2 | 9 | 27.8 | 11 |

* The 2nd branch includes another mixer and IF amplifier, which increases the total current consumption of the MCM to be 315 mA.



Printed Circuit Board Material: .014" FR-4, 4 layers, .062" total thickness



CV221-2A: The application circuit can be broken up into three main functions as denoted in the colored dotted areas above: RF/IF diplexing (blue), IF amplifier matching (green), and dc biasing (purple). There are various placeholders for chip components in the circuit schematic so that a common PCB can be used for all WJ dual-branch converters.

versions only)

External Diplexer: This is only used with the cellular-band CV products. The mixer performs the diplexing internally for the CV221-2A; therefore the components shown in the diplexer section should be not be loaded except for L3, L10, L7, and L11, which should contain a $0~\Omega$ jumper.

IF Amplifier Matching: The IF amplifier requires matching elements to optimize the performance of the amplifier to the desired IF center frequency. Since IF bandwidths are typically on the order

of 5 to 10%, a simple two element matching network, in the form of either a high-pass or low-pass filter structure, is sufficient to match the MMIC IF amplifier over these narrow bandwidths. Proper component values for other IF center frequencies can be provided by emailing to applications.engineering@wj.com.

DC Biasing: DC bias must be provided for the LO and IF amplifiers in the converter. R1 sets the operating current for the last stage of the LO amplifier and is chosen to optimize the mixer LO drive level. Proper RF chokes and bypass capacitors are chosen for proper amplifier biasing at the intended frequency of operation. The "+5 V" dc bias should be supplied directly from a voltage regulator.

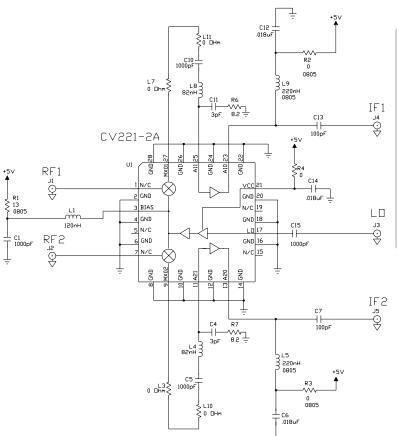
WiMax Operation: There is no change to the application circuit for operation in the 2.5 to 2.7 GHz band.

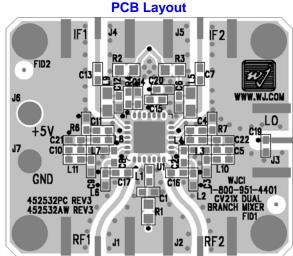
Specifications and information are subject to change without notice

Bias



Application Circuit: IF = 240 MHz (CV221-2APCB240) RF = 1900 - 2700 MHz, IF = 240 MHz





Circuit Board Material: .014" FR-4, 4 layers, .062" total thickness

Bill of Materials

| Ref. Desig. | Component | Size |
|--|--|------|
| R1 ⁽¹⁾ | 13 Ω chip resistor | 0805 |
| R2, R3, R4, L3, L7 L10, L11 | 0 Ω chip resistor | 0603 |
| R6, R7 | 8.2 Ω chip resistor | 0603 |
| C1, C5, C10, C15 | 1000 pF chip capacitor | 0603 |
| C4, C11 (2) | 3 pF chip capacitor | 0603 |
| C6, C12, C14 | .018 μF chip capacitor | 0603 |
| C7, C13 | 100 pF chip capacitor | 0603 |
| L1 | 120 nH chip inductor | 0603 |
| L4, L8 ⁽²⁾ | 82 nH chip inductor | 0603 |
| L5, L9 | 220 nH chip inductor | 0805 |
| C2, C3, C8, C9, C16 C17, C19, C20, C21 C22, L2, L6 | Shown on silkscreen, but not used in actual circuit. | |
| U1 | CV221-2A WJ Converter | QFN |

Notes:

- 1. The R1 resistor can be modified for the CV221-2A to draw less current. Changing it from 13 to 18Ω is expected to have the converter draw 17mA less current so that the converter will draw about 300mA typically under LO drive, while degrading the IIP3 performance by 0.5 dB.
- 2. The values shown above have the IF tuned at 240 MHz and will affect the optimal performance of the converter. For other frequencies, these components need to be modified as follows:

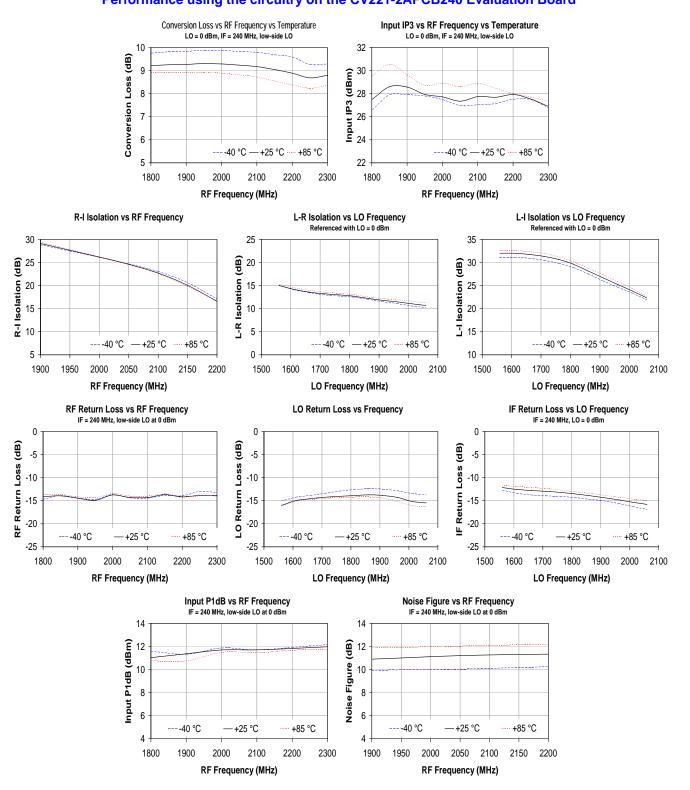
IF Amplifier Matching

| Ref. Desig. | 50 | 70 | 75 | 100 | 120 | 130 | 140 | 155 | 180 | 240 |
|-------------|--------|--------|--------|--------|--------|-------|--------|--------|--------|--------|
| C4, C11 | 18 pF | 15 pF | 15 pF | 8.2 pF | 8.2 pF | 6.8pF | 5.6 pF | 5.6 pF | 3.9pF | 3.0 pF |
| L4, L8 | 390 nH | 220 nH | 220 nH | 180 nH | 150 nH | 150nH | 150 nH | 120 nH | 110 nH | 82 nH |





Typical Downconversion Performance Plots Performance using the circuitry on the CV221-2APCB240 Evaluation Board

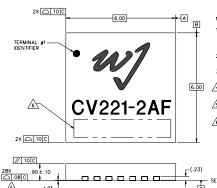




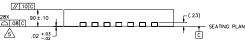
CV221-2AF Mechanical Information

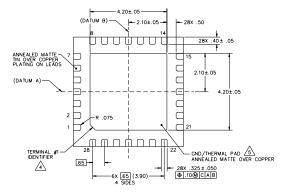
This package is lead-free/RoHS-compliant. The plating material on the pins is annealed matte tin over copper. It is compatible with both lead-free (maximum 260 °C reflow temperature) and leaded (maximum 245 °C reflow temperature) soldering processes.

Outline Drawing

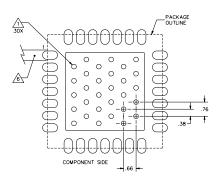


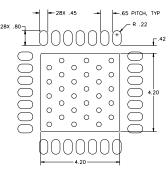
- EXCEPT WHERE NOTED, THIS PART OUTLINE CONFO TO JEDEC STANDARD MO-220, ISSUE E (VARIATIO VJJC) FOR THERMALLY ENHANCED PLASTIC VERY FINE PITCH QUAD FLAT NO LEAD PACKAGE (QFN).
- DIMENSIONING & TOLERANCING CONFORM TO ASME
- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION CONFORM TO JESD 95-1 SPP-012.
- COPLANARITY APPLIES TO THE EXPOSED GROUND/THERMAL PAD AS WELL AS THE TERMINALS.
- ALPHA-NUMERIC LOT CODE.

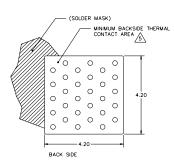




Mounting Configuration / Land Pattern







NOTES:

- GROUND/THERMAL WAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. WAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010"). ⚠
- ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
- TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
- ADD MOUNTING SCREWS NEAR THE PART TO FASTEN THE BOARD TO A HEATSINK. ENSURE THAT THE GROUND/THERMAL VIA REGION CONTACTS THE HEATSINK
- DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.
- RF TRACE WIDTH DEPENDS UPON THE PC BOARD MATERIAL AND CONSTRUCTION.
- USE 1 OZ. COPPER MINIMUM.
- ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES

Product Marking

The component will be lasermarked with a "CV221-2AF" product label with an alphanumeric lot code on the top surface of the package.

Tape and reel specifications for this part will be located on the website in the "Application Notes" section.

ESD / MSL Information



Caution! ESD sensitive device.

ESD Rating: Class 1B

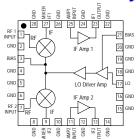
Value: Passes /500V to <1000V Human Body Model (HBM) Test: JEDEC Standard JESD22-A114 Standard:

ESD Rating: Class III

Value: Passes /500V to <1000V Charged Device Model (CDM) Test: Standard: JEDEC Standard JESD22-C101

MSL Rating: Level 2 at +260 °C convection reflow JEDEC Standard J-STD-020 Standard:

Functional Pin Layout



| _ | | _ 3 | _ |
|-----|-------------------------------|-----|-------------------------------|
| Pin | Function | Pin | Function |
| 1 | Ch. 1 Mixer RF Input | 15 | N/C or GND |
| 3 | LO Amp Bias | 17 | LO input |
| 5 | N/C or GND | 19 | N/C or GND |
| 7 | Ch. 2 Mixer RF Input | 21 | +5 V |
| 9 | Ch. 2 Mixer IF Output | 23 | Ch. 1 IF Amp Output / Bias |
| 11 | Ch. 2 IF Amp Input | 25 | Ch. 1 IF Amp Input |
| 13 | Ch. 2 IF Amp Output / Bias | 27 | Ch. 1 Mixer IF Output |

The even numbered pins are hard grounded to the backside paddle internally. They can be grounded or not connected. The backside paddle is required to be grounded.